PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date	
Kohei Seyama	08/02/2010	
Yutaka Kondo	08/02/2010	
Osamu Kakutani	07/30/2010	
Shigeru Hayata	08/02/2010	

RECEIVING PARTY DATA

Name:	SHINKAWA LTD.
Street Address:	51-1, Inadaira 2-chome, Musashimurayama-shi
City:	Tokyo
State/Country:	JAPAN
Postal Code:	208-8585

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	12841386

CORRESPONDENCE DATA

Fax Number: (212)940-8986

Correspondence will be sent via US Mail when the fax attempt is unsuccessful.

 $\overline{\neg \Gamma}$

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ATTORINET BOOKET NOMBER.	ATTORNEY DOCKET NUMBER:	SHIN 24.426
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NAME OF SUBMITTER: James J. Dade

Total Attachments: 2

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ASSIGNMENT

Docket No. SHIN 24.426

WHEREAS, the below named inventor, ASSIGNOR, has made a certain new and useful invention in:
BONDING APPARATUS AND BONDING STAGE HEIGHT ADJUSTMENT METHOD FOR THE
BONDING APPARATUS
for which
(check one) [] an application is being filed concurrently herewith,
[X] an application for a Patent of the United States was filed on July 22, 2010
and given Application Serial No. 12/841,386
and WHEREAS, SHINKAWA LTD having a place of business at 51-1, Inadaira 2-chome, Musashimurayama-shi,
Tokyo 208-8585, Japan ASSIGNEE
is desirous of obtaining the entire right, title and interest in, to and under the said invention and the said application.
NOW, THEREFORE, in consideration of the sum of One Dollar (\$1.00) to me in hand paid, and other good and valuable consideration, the receipt of which is hereby acknowledged, the said ASSIGNOR has sold, assigned, transferred and set over, and by these presents does hereby sell, assign, transfer and set over, unto the said ASSIGNEE, its successors, legal representatives and assigns, the entire right, title and interest in, to and under the said invention, and the said United
States application and all divisions, renewals and continuations thereof, and all Patents of the United States which may be granted thereon and all reissues and extensions thereof; and all applications for industrial property protection, including, without limitation, all applications for patents, utility models, and designs which may hereafter be filed for said invention in any country or countries foreign to the United States, together with the right to file such applications and the right to claim for the same the priority rights derived from said United States application under the Patent Laws of the United States, the International Convention for the Protection of Industrial Property, or any other international agreement or the domestic laws of the country in which any such application is filed, as may be applicable; and all forms of industrial property protection, including, without limitation, patents, utility models, inventor's certificates and designs which may be granted for said invention in any country or countries foreign to the United States and all extensions, renewals and reissues thereof;
ASSIGNOR authorizes and requests the Commissioner of Patents and Trademarks of the United States, and any Official of any country or countries foreign to the United States, whose duty it is to issue patents or other evidence or forms of industrial property protection on applications as aforesaid, to issue the same to the said ASSIGNEE, its successors, legal representatives and assigns, in accordance with the terms of this instrument; and
ASSIGNOR covenants and agrees that he has full right to convey the entire interest herein assigned, and has not executed, and will not execute, any agreement in conflict herewith; and
ASSIGNOR further covenants and agrees that he will communicate to the said ASSIGNEE, its successors, legal representatives and assigns, any facts known respecting said invention, and testify in any legal proceeding, sign all lawful papers, execute all divisional, continuing, reissue and foreign applications, make all rightful oaths, and generally do everything possible to aid the said ASSIGNEE, its successors, legal representatives and assigns, to obtain and enforce proper protection for said invention in all countries.
Full name of first inventor Kohei Seyama
Inventor's Signature Cohe Seyama Date Acy 2 2010
Residence Tokyo, Japan Citizenship Japan
Post Office Address c/o SHINKAWA LTD., 51-1, Inadaira 2-chome
Musashimurayama-shi, Tokyo, 208-8585, Japan
Full name of second inventor Yutaka Kondo Inventor's Signature Date Aug 2, 2010
Residence Tokyo, Japan Citizenship Japan
Post Office Address c/o SHINKAWA LTD., 51-1, Inadaira 2-chome
Museshimurayama shi Talaya 208 8595 Janan

PATENT REEL: 024772 FRAME: 0474

Full name of third inventor	Osamu Kakutani				
Inventor's Signature	Osamu dalutani	Date	<u>July</u>	<u> 30 . </u>	2010
Residence Tokyo, Japan		Citizenship	Japan		
Post Office Address c/o S	HINKAWA LTD., 51-1, Inadair	a 2-chome			
Musa	ashimurayama-shi, Tokyo, 208-8	585, Japan			
	•				
Full name of fourth inventor	Shigeru Hayata				
Inventor's Signature	Shizery Hayata	Date	Aug	$\frac{2}{2}$, 2	1010
Residence Tokyo, Japan		Citizenship	Japan 0		
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